

CLAIMS

1. A solid-state imaging apparatus comprising:

a solid-state imaging element, having an energy ray sensitive portion;

5 a signal processing circuits, processing signals output from said solid-state imaging element; and

a package, housing the solid-state imaging element and the signal processing circuit,

10 wherein the signal processing circuit is positioned at a planar portion of the package that differ from a planar portion at which the solid-state imaging element is positioned.

2. A solid-state imaging apparatus comprising:

a solid-state imaging element, having an energy ray sensitive portion;

15 a signal processing circuit, processing signals output from the solid-state imaging element; and

a package, housing the solid-state imaging element and the signal processing circuit,

20 wherein the package has a first planar portion and a second planar portion, formed to be stepped with respect to the first planar portion, and

wherein the solid-state imaging element is positioned at the first planar portion, and the signal processing circuit is positioned at the second planar portion.

25 3. The solid-state imaging apparatus according to Claim 1 or 2, wherein the signal processing circuit includes a load resistor that is

electrically connected to an output terminal of the solid-state imaging element.

4. The solid-state imaging apparatus according to Claim 1 or 2, wherein the signal processing circuit comprises:

5 a load resistor, one end of which is electrically connected to an output terminal of the solid-state imaging element and the other end of which is grounded; and

 a buffer amplifier, having a bipolar transistor that is electrically connected to the output terminal of the solid-state imaging element.